

# **Covid-19 impact on Global and China Wafer Grinding Tapes Market: Market Segments: By Type (UV Type, Non-UV Type); By End Users (Standard, Standard Thin Die, (S)DBG(GAL), and Bump); and Region – Analysis of Market Size, Share & Trends for 2014 – 2019 and Forecasts to 2030**

<https://marketpublishers.com/r/CD4258CA8ED2EN.html>

Date: May 2024

Pages: 152

Price: US\$ 5,000.00 (Single User License)

ID: CD4258CA8ED2EN

## **Abstracts**

### **Product Overview**

Wafer Grinding Tapes are used to cover the wafer surface during wafer grinding after the IC is established on the wafer. Attached to the circuit surface, it avoids damage to the circuit surface and contamination of the wafer surface and increases the grinding accuracy of the wafer. It can perfectly protect the surface of the wafer pattern and the chip during the manufacturing process with its excellent physical and chemical properties. With the production of jumbo-sized and thinned wafers and high-bumped wafers, the functions needed for BG tape are- low levels of contamination, very near contact with wafers, and ease of peeling.

### **Market Highlights**

Global and China Wafer Grinding Tapes market is expected to project a notable CAGR in 2030.

Global and China Wafer Grinding Tapes market to surpass USD XXXX million by 2030 from USD XXXX million in 2018 at a CAGR of XX% throughout the forecast period, i.e. 2019-30. The Global and China Wafer Grinding Tapes market is expected to observe growth in the future. The increase in the need for semiconductor wafer manufacturing for the development of electrical and photonic circuits is driving the growth of the market. Continuous growth in the semiconductor industry is also fueling the growth of the wafer grinding tape market.

### Recent Highlights of Global and China Wafer Grinding Tapes Market:

Shanghai Jita Semiconductor, a subsidiary of Huada Semiconductor and China Electronics Corporation (CEC), announced that it will develop 200 mm and 300 mm semiconductor fabs for analog and power semiconductors in Shanghai from 2019.

### Global and China Wafer Grinding Tapes Market: Segments

UV segment to grow with the highest CAGR during 2019-30

Global and China Wafer Grinding Tapes market is segmented by the network into UV and Non-UV. UV segment held the largest market share of XX.X% in the year 2018 and is anticipated to dominate the global market throughout the forecast period. Factors such as increased demand for ultra-thin wafers, increased need for wafer manufacturing, increased emphasis on wafer surface safety during the grinding process, and growth in the semiconductor industry are boosting the growth of the wafer grinding tape market globally.

Standard segment to grow with the highest CAGR during 2019-30

Global and China Wafer Grinding Tapes market is segmented by end-users into Standard, Standard Thin Die, (S)DBG(GAL), and Bump. Standard segment held the largest market share of XX.X% in the year 2018 and is expected to maintain this trend throughout the forecast period.

### Global and China Wafer Grinding Tapes Market: Market Dynamics

#### Drivers

#### Rise in Need for Wafer Fabrication

Semiconductor wafer manufacturing is a method that consists of a number of sequential processes for the manufacture of electrical circuits or semiconductor wafers. Wafer manufacturing helps in the production of components with the necessary electrical structures. Wafer manufacturing process is conducted for the processing of raw wafers to finished chips (discrete or integrated circuits). Factors such as high demand for silicon wafers and equipment footprint in the manufacturing process will support the global study of the manufacturing of semiconductor wafers and their equipment market in the future. Also, advances in wafer technologies that have led to denser packaging of devices such as MEMS (micro-electromechanical system) and transistors are expected to drive the need for wafer manufacturing processes globally in the semiconductor industry.

### Increase in Investment in Wafer Fabrication Equipment and Materials

There is an increase in the trend towards rising investment in wafer manufacturing

equipment and materials, which offers lucrative growth opportunities for the semiconductor industry. Governments in various developing regions, such as South Korea, Taiwan, and China, are creating regulations to enhance the semiconductor industry by implementing strategies such as market expansion, acquisition, and product launches, among others.

## Restraints

### Increase in Cost of Wafer Fabrication

Wafer grinding is a semiconductor chip manufacturing phase during which the wafer thickness is reduced to allow the stacking and high-density packaging of integrated circuits. It is the method of grinding the wafer to the proper wafer thickness before assembly. It's often referred to as wafer thinning. As wafer grinding tapes protect the wafer surface from contamination, there is an increasing shift from non-UV tapes to UV curable tapes. Also, these tapes incur additional costs as to non-UV wafer grinding tapes. This is supposed to contribute to the total cost of production of wafers by making it marginally costly. This rise in the change from non-UV to UV curable wafer grinding tapes raises the overall cost of wafer production, which is expected to impede the wafer grinding tape market to a certain extent.

### Covid-19 impact on Global and China Wafer Grinding Tapes Market

With the advent of coronavirus majority of industries have stopped their business operations due to social distancing norms and the supply chain has also been adversely affected since the raw materials are unable to reach the manufacturing units causing disturbances. However, the post-COVID-19 impact the demand for wafer back grinding tapes is expected to increase due to an increase in the need for semiconductor wafer manufacturing for photonic and electrical circuit development. These are expected to be key factors driving the global back melting tape market during the forecast period.

### Global and China Wafer Grinding Tapes Market: Regions

Global and China Wafer Grinding Tapes market is segmented based on regional analysis into five major regions. These include North America, Latin America, Europe, APAC, and MENA.

Global and China Wafer Grinding Tapes market in Asia Pacific held the largest market share of XX.X% in the year 2018 and will continue to dominate the market throughout the forecast period. Asia Pacific is the leading user of wafer-back grinding tape, followed by North America and Europe. China and India are the main markets for the region. In terms of production, the two countries account for a large share of the wafer back grinding tape market in the region. The increase in demand for wafer back grinding

tapes in Asia Pacific can be attributed to a continuous increase in industrialization and an increase in the need for consumer electronics in the region.

Global and China Wafer Grinding Tapes market is further segmented by region into:  
North America Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – United States and Canada

Latin America Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – Mexico, Argentina, Brazil, and Rest of Latin America

Europe Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – United Kingdom, France, Germany, Italy, Spain, Belgium, Hungary, Luxembourg, Netherlands, Poland, NORDIC, Russia, Turkey, and Rest of Europe

APAC Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – India, China, South Korea, Japan, Malaysia, Indonesia, New Zealand, Australia, and Rest of APAC

MENA Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – North Africa, Israel, GCC, South Africa, and Rest of MENA

Global and China Wafer Grinding Tapes: Key Players

Mitsui Chemicals Tohcello

Company Overview

Business Strategy

Key Product Offerings

Financial Performance

Key Performance Indicators

Risk Analysis

Recent Development

Regional Presence

SWOT Analysis

Nitto

LINTEC

Furukawa Electric

Denka

D&X

AI Technology

Force-One Applied Materials

AMC Co, Ltd

Pantech Tape Co., Ltd

Other Prominent Players

Global and China Wafer Grinding Tapes market report also contains analysis on:

Wafer Grinding Tapes Market Segments:

By Type

UV  
Non-UV  
By End-Users  
Standard  
Standard Thin Die  
(S)DBG(GAL)  
Bump  
Wafer Grinding Tapes Market Dynamics  
Wafer Grinding Tapes Market Size  
Supply & Demand  
Current Trends/Issues/Challenges  
Competition & Companies Involved in the Market  
Value Chain of the Market  
Market Drivers and Restraints

## Contents

### **1. EXECUTIVE SUMMARY**

### **2. GLOBAL AND CHINA WAFER GRINDING TAPES MARKET**

- 2.1. Product Overview
- 2.2. Market Definition
- 2.3. Segmentation
- 2.4. Assumptions and Acronyms

### **3. RESEARCH METHODOLOGY**

- 3.1. Research Objectives
- 3.2. Primary Research
- 3.3. Secondary Research
- 3.4. Forecast Model
- 3.5. Market Size Estimation

### **4. AVERAGE PRICING ANALYSIS**

### **5. MACRO-ECONOMIC INDICATORS**

### **6. MARKET DYNAMICS**

- 6.1. Growth Drivers
- 6.2. Restraints
- 6.3. Opportunity
- 6.4. Trends

### **7. CORRELATION & REGRESSION ANALYSIS**

- 7.1. Correlation Matrix
- 7.2. Regression Matrix

### **8. RECENT DEVELOPMENT, POLICIES & REGULATORY LANDSCAPE**

### **9. RISK ANALYSIS**

9.1. Demand Risk Analysis

9.2. Supply Risk Analysis

## **10. GLOBAL AND CHINA WAFER GRINDING TAPES MARKET ANALYSIS**

10.1. Porters Five Forces

10.1.1. Threat of New Entrants

10.1.2. Bargaining Power of Suppliers

10.1.3. Threat of Substitutes

10.1.4. Rivalry

10.2. PEST Analysis

10.2.1. Political

10.2.2. Economic

10.2.3. Social

10.2.4. Technological

## **11. GLOBAL AND CHINA WAFER GRINDING TAPES MARKET**

11.1. Market Size & forecast, 2019A-2030F

11.1.1. By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

11.1.2. By Volume (Million Units) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

## **12. GLOBAL AND CHINA WAFER GRINDING TAPES MARKET: MARKET SEGMENTATION**

12.1. By Regions

12.1.1. North America:(U.S. and Canada) By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

12.1.2. Latin America: (Brazil, Mexico, Argentina, Rest of Latin America) By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

12.1.3. Europe: (Germany, UK, France, Italy, Spain, BENELUX, NORDIC, Hungary, Poland, Turkey, Russia, Rest of Europe) By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

12.1.4. Asia-Pacific: (China, India, Japan, South Korea, Indonesia, Malaysia, Australia, New Zealand, Rest of Asia Pacific) By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

12.1.5. Middle East and Africa: (Israel, GCC, North Africa, South Africa, Rest of Middle East and Africa) By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

## 12.2. By Type: Market Share (2020-2030F)

12.2.1. UV, By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

12.2.2. Non-UV, By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

## 12.3. By End-Users: Market Share (2020-2030F)

12.3.1. Standard, By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

12.3.2. Standard Thin Die, By Value (USD Million) 2019-2030F; Y-o-Y Growth (%)  
2020-2030F

12.3.3. (S)DGB(GAL), By Value (USD Million) 2019-2030F; Y-o-Y Growth (%)  
2020-2030F

12.3.4. Bump, By Value (USD Million) 2019-2030F; Y-o-Y Growth (%) 2020-2030F

## 13. COMPANY PROFILE

### 14. MITSUI CHEMICALS TOHCELLO

14.1. Company Overview

14.2. Company Total Revenue (Financials)

14.3. Market Potential

14.4. Global Presence

14.5. Key Performance Indicators

14.6. SWOT Analysis

14.7. Product Launch

### 15. NITTO

### 16. LINTEC

### 17. FURUKAWA ELECTRIC

### 18. DENKA

### 19. D&X

### 20. AI TECHNOLOGY

### 21. FORCE-ONE APPLIED MATERIALS

### 22. AMC CO, LTD



## **23. PANTECH TAPE CO., LTD**

## **24. OTHER PROMINENT PLAYERS**

Consultant Recommendation

**\*\*The above-given segmentations and companies could be subjected to further modification based on in-depth feasibility studies conducted for the final deliverable**

## I would like to order

Product name: Covid-19 impact on Global and China Wafer Grinding Tapes Market: Market Segments: By Type (UV Type, Non-UV Type); By End Users (Standard, Standard Thin Die, (S)DBG(GAL), and Bump); and Region – Analysis of Market Size, Share & Trends for 2014 – 2019 and Forecasts to 2030

Product link: <https://marketpublishers.com/r/CD4258CA8ED2EN.html>

Price: US\$ 5,000.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

[info@marketpublishers.com](mailto:info@marketpublishers.com)

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/CD4258CA8ED2EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:

Last name:

Email:

Company:

Address:

City:

Zip code:

Country:

Tel:

Fax:

Your message:

**\*\*All fields are required**

Customer signature \_\_\_\_\_

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below  
and fax the completed form to +44 20 7900 3970